

Amendments to the Drawings:

The attached sheets of drawings formalize all figures (Fig. 1-Fig. 3G) as replacements to the informal figures originally filed. Sheet 1 which includes Figs. 1A-1D, replaces Figs. 1A-1D on the original sheet. Sheet 2 which includes Fig. 2, replaces Fig. 2 on the original sheet. Sheet 3 which includes Figs. 3A-3C, replaces Figs. 3A-3C on the original sheet. Sheet 4 which includes Figs. 3D-3F, replaces Figs. 3D-3F on the original sheet. Sheet 5 which includes Fig. 3G replaces Fig. 3G on the original sheet. Applicant submits no substantive changes have been made to any figure.

Attachment: Replacement Sheets 1/5-5/5

REMARKS

With this Response, claims 1 and 14 have been amended, no claim has been added or canceled. Therefore, claims 1-7, 9-10, 14-18, 20, 22-28 are pending.

ALLOWABLE SUBJECT MATTER

Applicant acknowledges that claims 24-28 were found allowable.

Applicant further acknowledges that claims 4-7, 9, 15-18 and 20 were found to have allowable subject matter. Specifically, these claims were objected to as being dependent upon rejected base claims, but would be allowable if rewritten in independent form. Applicant respectfully submits that the rejection of the base claims is overcome herein, meaning that these claims are allowable as written. Applicant therefore respectfully requests that the objection to these claims be withdrawn.

CLAIM REJECTIONS - 35 U.S.C. § 102

Claims 1-3, 10, 14, 22 and 23 were rejected under 35 U.S.C. § 102(b) as being anticipated by US Patent No. 6,114,201 to Wu (hereinafter "Wu").

Claims 1-10

Applicant has amended claim 1 to correct the accidental deletion of the word "removing" from claim 1 that occurred in Applicant's Response to Restriction Requirement mailed March 10, 2006. Applicant directs the Examiner's attention to the Office Action Response mailed November 30, 2005 which shows claim 1 as amended included the word "removing" as the amended claim now reads. Applicant respectfully requests the Examiner to enter the amendment so that claim 1 is returned to its properly amended form.

Applicant's independent claim 1 recites, in part, "forming one or more trenches in the trench layer exposing the semiconductor substrate." An embodiment of this operation is depicted in Applicant's Fig. 3C. In contrast, Wu discloses the substrate to be material 2 in Figs. 2-11. (Wu, col. 4, line 6). Referring to Wu's Fig. 6, it is Applicant's position that trench 34 is never "exposing the semiconductor substrate," and instead is merely exposing layer 20 and the "plug" 26, which are both formed over Wu's substrate 2.

Also, Applicant's claim 1 recites, "removing a portion of the trench layer to expose the semiconductor material as one or more semiconductor fins." An embodiment of this operation is shown in Applicant's Fig. 3F. In contrast, referring to Wu Fig. 4, it is Applicant's position that the plug 26 is never exposed as one or more semiconductor fins because no portion of layers 18 and 20 are subsequently removed (Wu Figs. 4-11). Instead, Applicant understands Wu to retain all of layers 18 or 20 after plug 26 is formed.

Therefore, it is Applicant's position that Wu fails to disclose all the features of Applicant's claim 1. For at least this reason, claims 2-10, dependent upon claim 1, should also be allowable.

Claims 14-23

Applicant's independent claim 14 recites, in part, "filling the one or more trenches with a semiconductor material contacting said semiconductor substrate." As previously discussed in regards to Applicant's claim 1, it is Applicant's position that Wu's trench 34 is never "exposing the semiconductor substrate," and instead is merely exposing layer 20 and the "plug" 26. Because the trench 34 never exposes the semiconductor substrate, it is Applicant's position that Wu's material 38, filling trench 34, is not "contacting said semiconductor substrate."

Furthermore, Applicant's claim 14 recites, in part, "selectively etching a remainder of the second oxide layer such that one or more semiconductor bodies are formed from the semiconductor material." As previously discussed in regards to Applicant's claim 1, it is Applicant's position that Wu's plug 26 is never exposed as one or more semiconductor bodies by removing in layers 18 and 20.

Therefore, it is Applicant's position that Wu fails to disclose all the features of Applicant's claim 14. For at least this reason, claims 15-23, dependent upon claim 14, should also be allowable.

On this basis Applicant respectfully requests the Examiner to remove the 35 U.S.C. §102 rejections of claims 1-3, 10, 14, 22 and 23.

CONCLUSION

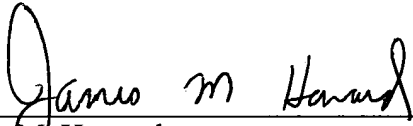
Applicant respectfully requests examination of the above-identified application in view of the response.

For at least the foregoing reasons, Applicant submits that the rejections of the claims have been overcome herein, placing all pending claims in condition for allowance. Such action is earnestly solicited. The Examiner is respectfully requested to contact the undersigned by telephone if such contact would further the examination of the above-identified application.

The Commissioner is authorized to charge or credit any deficiencies or overpayments in connection with this submission to Deposit Account No. 02-2666, and is requested to notify us of same.


Respectfully submitted,
BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN, LLP

Date: November 1, 2006


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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail on the below date with sufficient postage in an envelope addressed to: Mail Stop RCE, Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450

Signature:  Date: 11/01/06
Theresa Belland